



Telops specializes in the design and production of sophisticated opto-electronic systems for the defence, aerospace and telecommunications industries. In addition to providing specialized opto-electronic engineering services, Telops has also developed the Hyper-Cam, an infrared hyperspectral imager which allows standoff chemical detection at a distance of up to five kilometers. This advanced, lightweight, compact, imaging radiometric solution can enable its user to measure different spectrum and then compare the measured spectrum with the signatures of known gases and solids. The constituents and properties of a target can then be easily identified. This powerful tool can then be used in a multitude of applications including:

- Military
  - Standoff chemical detection and identification
  - Signatures of rockets, missiles and flares
  - Military target signature analysis
  - Detection of mines and improvised explosive devices (IED)
- Airborne
  - Hyperspectral mapping of the ground or atmosphere
- Research or Lab
  - Geology and mineralogy studies
  - Surface emissivity studies
  - Gaseous cloud studies
- Environmental
  - Leak detection
  - Pollution monitoring
  - Forest fire monitoring
  - Flare measurement

Telops also offers R&D services for optical system technology development. Telops experts deliver significant expertise in the fields of opto-electronic systems engineering with full disciplinary specialist in optical, mechanical, electronics, thermal, software and system engineering. Telops works closely with its clients/scientists to develop customized optical solutions in the area of infrared remote sensing, spectrometry, cryogenic and ruggedized optical systems as well as dedicated imaging and calibration systems.

Another Telops specialty is the design and production of advanced manufacturing, burn-in, lifestest and characterization solutions for high power laser diodes, modules and other photonic devices. Telops optimizes development and manufacturing processes with COTS or customized solutions adapted to meet clients needs and specifications. Photonic device manufacturing systems include wafer scribing / cleaving, stacking / unstacking of edge emitters (pre/post reflective coating), fully automated test and inspection (for wafers, bars, chips and devices) and more.

Telops are the professionals for your high-reliability optronics systems worldwide. With state-of-the art expertise and technology, Telops works in close collaboration with its clients, respecting their specifications and needs, in order to deliver the best performing, most rugged and dependable solutions available.